

5	6
20.5	out @ 7.5A Max. Continuous

Cx2 10uF 50V

Cx1 10uF 50V Cx3 10uF 50V

+ C4 330µF 25V

TP7 TP3

TP8

● TP4

575-8

575-8

v<u>о</u>uт

10uF 50V

1. All components with an "x" suffix are components that were not part of the original design and have no placeholders on the PCB. These components were kludged onto the board after PCB

2. Design is built on the PMP7924 RevA PCB.

	Designed for: Public Release	Mod. D	ate: 11/2	9/2017	
	Project Title: LM5122 Single-Phase Sync Boost				JIA TEX
Rev: A	Sheet Title: Schematic				
ntrol disabled	Assembly Variant: 001		Sheet: 1	of 2	
	File: PMP21277_BlankSheet.	.SchDoc	Siz	e: B	http://w
rian	Contact: http://www.ti.com/su	upport			© Texas Inst
-				<u> </u>	



1	2	3	4	5	6







PCB LOGO



1

в

С

D

Variant/Label Table			
Variant	Label Text		
001			

		Number: PN
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warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose,	se, or will operate in an implementation. Texas Instruments and/or its	Drawn By:
licensors do not warrant that the design is production worthy. You should completely validate and test your design impl	nplementation to confirm the system functionality for your application.	Engineer: H
2 3	4	

 Orderable: N/A
 Designed for: Public Release
 Mod. Date: 11/28/2017

 TID #:
 PMP21277
 Project Title: LM5122 Single-Phase Sync Boost

 Number: PMP21277
 Rev: A
 Sheet Title: Hardware

 SVN Rev:
 Version control disabled
 Assembly Variant: 001
 Sheet: 2 of 2

 Drawn By:
 File: PMP21277_EVM. Hardware.SchDoc
 Size: B
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 Engineer: Hrag Kasparian
 Contact: http://www.ti.com/support
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 5
 6

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